EV GROUP AND PANASONIC TEAM UP ON RESIST PROCESSING SOLUTION FOR PLASMA DICING

St. Florian, Austria / Osaka, Japan -- EV Group (EVG) and Panasonic Smart Factory Solutions Co., Ltd. announced today that both companies have teamed up to provide a novel resist processing solution for plasma dicing that is developed for emerging applications, such as Internet of Things (IoT) sensors, MEMS, RFID, CMOS image sensors and thinned memories. This advanced solution, which incorporates the EVG®100 series of resist processing systems and Panasonic's APX300 Dicer Module plasma dicer, became available from March 13, 2019.

Plasma dicing enables highly parallel and high-throughput die singulation for small devices such as sensors, MEMS and RFID chips. It also provides debris- and particle-free die singulation to enable high process yields for CMOS image sensors, as well as damage-free and high-quality chip sidewalls for thinned memories.

Plasma dicing brings new pre-process requirements, including the need for thick resist coating (several dozen microns in thickness) on the wafer's surface prior to lithography or laser patterning processes to open up the dicing lanes. However, uniform protective coating of structures on the surface, such as multilayer interconnections and bumps, is critical with traditional spin-coating techniques.

The EVG100 series of resist processing systems with EVG's proprietary OmniSpray® technology enables conformal non-dependent to topography coating of surfaces and bumps across the wafer.

Panasonic has installed the EVG100 series in its Plasma Dicing Demonstration Center in Kadoma City, Osaka, Japan, to develop high-throughput and high-quality dicing solutions by leveraging its APX300 Dicer Module combined with the preprocesses of uniform resist coating on the bumps and subsequent patterning of dicing streets enabled by the EVG100 series.

EVG and Panasonic will begin providing this novel resist coating solution to improve dicing quality and productivity through customer demonstrations in the Plasma Dicing Demonstration Center.

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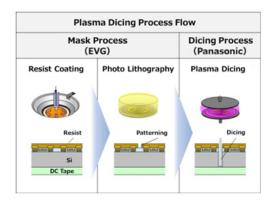
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EVG®150 Automated Resist Processing system:



Resist Coating on Bump (EVG)

Solder ball

PR
12 pm
10 pm
After Patterning (Photo Lithography)

Panasonic Smart Factory Solutions' APX300 Dicer Module:



*The content in the following news releases is accurate at the time of publication but may be subject to change without notice. Please note therefore that these documents may not always contain the most up-to-date information.